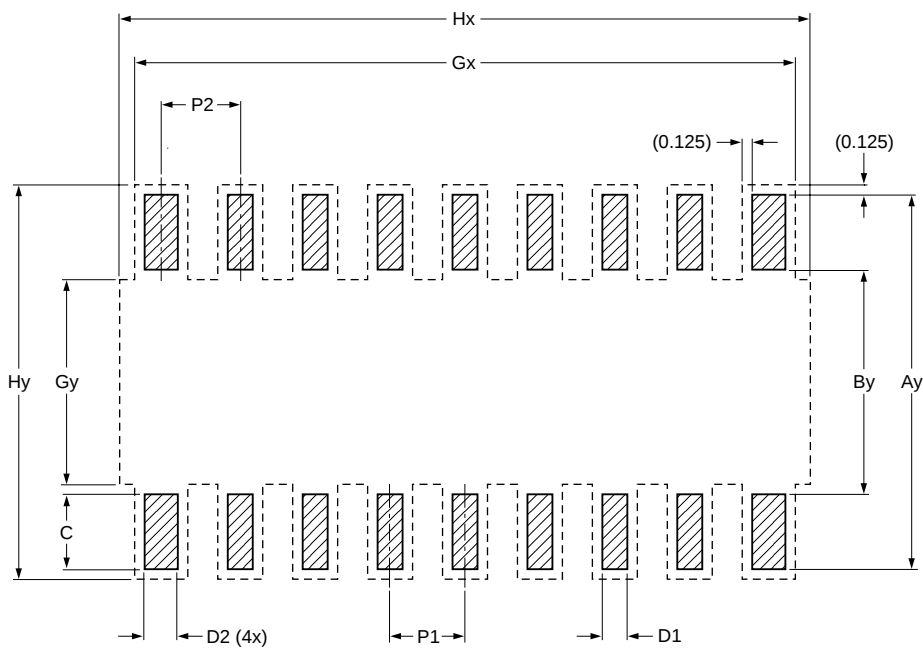


Footprint information for reflow soldering of VSO40 package

SOT158-1



Generic footprint pattern
Refer to the package outline drawing for actual layout

 solder land
 occupied area

DIMENSIONS in mm

P1	P2	Ay	By	C	D1	D2	Gx	Gy	Hx	Hy
0.760	0.835	12.700	8.300	2.200	0.450	0.600	15.440	8.100	16.100	12.950